For Immediate Release

Pac Tech GmbH
RE: PacLine 300/Diodes Incorporated
February 7, 2012

Nauen, Germany – February 7, 2012 — Pac Tech – Packaging Technologies GmbH announces that it has sold their latest PacLine 300 A50 system for electroless deposition of Ni, Pd and Au on advanced semiconductors to Diodes Incorporated in Plano, Texas. The system will be installed at Diodes wafer fabrication facility in Kansas City, Missouri.

The PacLine 300 A50 is a fully automated, self-contained, mass-production system capable of processing up to 150 wafers per hour and up to 600,000 8-inch wafers per year with full robotic handling of wafer carriers. The system is part of a turnkey process technology transfer, including Pac Tech's proprietary process know-how and unique chemical product line. The state-of-the-art plating line will be equipped with fully automated chemical delivery unit (CDU) and will use a SECS GEM interface to communicate with the facility host system. As every Pac Tech equipment the design, hardware and software are conform to SEMI S2/S8/S14 standards.

The PacLine 300 A50 provides fully automatic bath controls, including automatic titration, temperature and flow control as well as pH measurements and replenishment. The electroless Ni and Pd process technology will enable Diodes to utilize high volume production capability at low processing cost due to parallel wafer processing for their packaging needs. One of the additional advantages of electroless plating is the absence of any tooling and sequential wafer processing such as lithography and sputtering.

In general ENIG and ENEPIG metallizations are compatible with a variety of applications, e.g. UBM for WLCSP and flip-chip, frontside metallization for Power MOSFET for clip attach soldering and OPM for Cu and Au wire-bonding.
It is compatible with all flip-chip or WLCSP assembly processes.

Dr. Thorsten Teutsch, President of Pac Tech USA says, "It is exciting to see that Pac Tech's low cost technologies automated equipment lines are assisting to keep manufacturing jobs secured in the US."

About Diodes Incorporated

Diodes Incorporated is a leading global manufacturer and supplier of high-quality application specific standard products within the broad discrete, logic, and analog semiconductor markets. Diodes serves the consumer electronics, computing, communications, industrial, and automotive markets.

Diodes' products include diodes, rectifiers, transistors, MOSFETs, protection devices, functional specific arrays, single gate logic, amplifiers and comparators, Hall-effect and temperature sensors; power management devices, including LED drivers, DC-DC

switching and linear voltage regulators, and voltage references along with special function devices, such as USB power switches, load switches, voltage supervisors, and motor controllers.

Diodes' corporate headquarters, logistics center, and America's sales office are located in Plano, Texas. Design, marketing, and engineering centers are located in Plano; San Jose, California; Taipei, Taiwan; Manchester, England; and Neuhaus, Germany. The company's wafer fabrication facilities are located in Kansas City, Missouri and Manchester, with two manufacturing facilities located in Shanghai, China, another in Neuhaus, and two joint venture facilities located in Chengdu, China. Additional engineering, sales, warehouse, and logistics offices are located in Fort Worth, Texas; Taipei; Hong Kong; Manchester; and Munich, Germany, with support offices located throughout the world. For further information visit Diodes' website: www.diodes.com.

About Pac Tech

Pac Tech GmbH, established 1995 and a group member of NAGASE & CO., LTD., manufactures equipment for the microelectronic and advanced packaging industry. They offer wafer-level bumping and packaging contract manufacturing out of Nauen, Germany (HQ), and through the 100% subsidiaries Pac Tech USA Inc., Silicon Valley, USA and Pac Tech Asia SDN. BHD., Penang, Malaysia. Since 2005 Pac Tech is able to support equipment customers in Asia/Far East via an established service center out of Bangkok, Thailand.

The equipment product line consists of solder jetting equipment (SB2-Jet), wafer-level solder ball transfer systems (Ultra-SB2), wafer-level solder rework equipment (Ultra-SB2 300 WLR), laser assisted flip-chip bonders (Laplace) and automatic wet chemical lines for high volume electroless Ni/Au and Ni/Pd/Au bumping (PacLine 300 A50).

The wafer-level packaging subcontractor services consist of wafer bumping with electroless Ni/Au or Ni/Pd Under Bump Metallization (UBM) for wafer-level solder bumping for flip-chip or WLCSP as well as Ni/Pd/Au for wire-bonding. Additionally, Pac Tech offers AOI, X-Ray inspection, BCB Repassivation, wafer-level redistribution, wafer-level backside metallization, wafer thinning, laser backside marking, wafer dicing, chip singulation, tape and reel services. All three Pac Tech facilities have a wafer bumping capacity of 600,000 wafers 8" or 150,000 12" each per year.

Since its inception Pac Tech has received more than 50 patents for products developed in areas relating to wafer bumping, flip-chip and chip-scale packaging, and laser-bonding technology. For additional information please visit Pac Tech's website: www.pactech.com.